

4 spraying a decapsulation fluid onto the integrated circuit package via an injection head

5
6 clamped to the integrated circuit package, said injection head having a nozzle disposed above the
7 integrated circuit package that is in fluid communication with an inlet port of said injection head,
and a return port that is in fluid communication with an outlet port of said injection head.

14. The method as recited in claim 13, further comprising the step of controlling a flow
2 of the decapsulation fluid through a pair of tubes that couple an extender to said injection head
3 using a corresponding pair of valves.

15. The method as recited in claim 13, further comprising the step of plugging a stub
2 that supports the printed circuit board into a substrate.

16. The method as recited in Claim 13 further comprising the step of forming a seal
2 between said injection head and said integrated circuit package. --

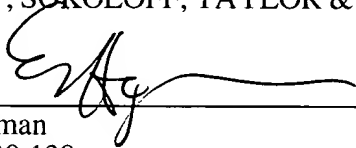
REMARKS

Entry of the foregoing amendments prior to the initial examination of the above-captioned
application is requested.

Respectfully submitted,

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